Wire-wound Ferrite Power Inductors LSRN series for General Electronic Equipment for Consumer Wire-wound Ferrite Power Inductors LLRN series for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

RELIABILITY DATA

1. Operating Temperature Range		
Specified Value	$-40 \sim +125^{\circ}C$	
Test Methods and Remarks	Including self-generated heat	

2. Storage Temperature Range			
Specified Value	-40~+85°C		
Test Methods and Remarks	-5 to 40°C for the product with taping.		

3. Rated current	
Specified Value	Within the specified tolerance

4. Inductance		
Specified Value	Within the specified tolera	ance
Test Methods and Remarks	Measuring equipment Measuring frequency	: LCR Meter(HP 4285A or equivalent) : 100kHz, 1V

5. DC Resistance		
Specified Value	Within the specified tolerar	nce
Test Methods and Remarks	Measuring equipment	: DC ohmmeter(HIOKI 3227 or equivalent)

6. Self resonance frequency		
Specified Value	-	

7. Temperature characteristic					
Specified Value	Inductance ch	Inductance change : Within $\pm 15\%$			
Test Methods and Remarks	With reference	of inductance shall be taken at temperature r e to inductance value at +20°C., change rate ximum inductance deviation in step 1 to 5 Temperature(°C) 20 Minimum operating temperature 20 (Standard temperature) Maximum operating temperature 20	-		

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8. Resistance to fle	xure of substrate		
Specified Value	No damage		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm. Test board size $: 100 \times 40 \times 1.0$ Test board material $:$ Glass epoxy-resin Solder cream thickness $: 0.15$ mm Land dimension Type A B C 101 2.5 5.6 3.2 125 2.5 8.6 3.2 125 2.5 8.6 3.2		
9. Insulation resista	nce : between wires		
Specified Value	-		
10. Insulation resist	ance : between wire and core		
Specified Value	-		
11 Withstanding vo	tage : between wire and core		
Specified Value			
Specified value			
12. Adhesion of terr			
Specified Value	Shall not come off PC board		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. Applied force : 10N to X and Y directions. Duration : 5s. Solder cream thickness : 0.15mm 10 N, 5 s		
13. Resistance to vibration			
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.		
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions. Frequency Range 10~55Hz Total Amplitude 1.5mm (May not exceed acceleration 196m/s ²) Sweeping Method 10Hz to 55Hz to 10Hz for 1min. X For 2 hours on each X, Y, and Z axis. Z For 2 hours on each X, Y, and Z axis.		

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Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

14. Solderability				
Specified Value	At least 90% of surface of terminal electrode is covered by new solder.			
	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux : Ethanol solution containing rosin 25%.			
Test Methods and Remarks	Solder Temperature	245±5°C		
Remarks	Time 5±1.0 sec.			
	XImmersion depth : All sides of mounting terminal shall be immersed.			

15. Resistance to soldering heat			
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.		
Test Methods and Remarks	The test sample shall be exposed to reflow oven at 230±5°C for 40 seconds, with peak temperature at 260±5°C for 5 seconds, 2 times. Test board material : Glass epoxy-resin Test board thickness : 1.0mm		

16. Thermal shock				
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.			
	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.			
	Step	Temperature (°C)	Duration (min)	
Test Methods and Remarks	1	-40 ± 3	30±3	
	2	Room temperature	Within 3	
	3	+85±2	30±3	
	4	Room temperature	Within 3	
	Recover	y : At least 2hrs of recovery	under the standard conditio	n after the test, followed by the measurement within 48hrs.

17. Damp heat				
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.			
	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table.			
Test Methods	Temperature	60±2°C		
and Remarks	Humidity	90~95%RH		
	Time	500+24/-0 hour		
	Recovery : At lea	st 2hrs of recovery under	the standard condition after the test, followed by the measurement within 48hrs.	

18. Loading under	damp heat			
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.			
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table.			
	Temperature	60±2°C		
	Humidity	90~95%RH		
	Applied current	Rated current		
	Time	500+24/-0 hour		
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			
19. Low temperatu	re life test			
Specified Value	Inductance change : Within \pm 10% No significant abnormality in appearance.			
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.			
	Temperature	-40±2°C		
	Time	500+24/-0 hour		
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			

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 20. High temperature life test

 Specified Value

21. Loading at high temperature life test					
Specified Value	Inductance change : Within $\pm 10\%$ No significant abnormality in appearance.				
	The test samples shall be soldered to the test board by the reflow soldering.				
Test Methods	Temperature	85±2°C			
and Remarks	Applied current	Rated current			
	Time	500+24/-0 hour			
	Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.				

22. Standard condition				
Specified Value	Standard test condition : Unless otherwise specified, temperature is 20±15°C and 65±20% of relative humidity. When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of 20±2°C of temperature, 65±5% relative humidity. Inductance is in accordance with our measured value.			

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